



Silicon nanowires for thermoelectric harvesting applications: growth, integration and characterization

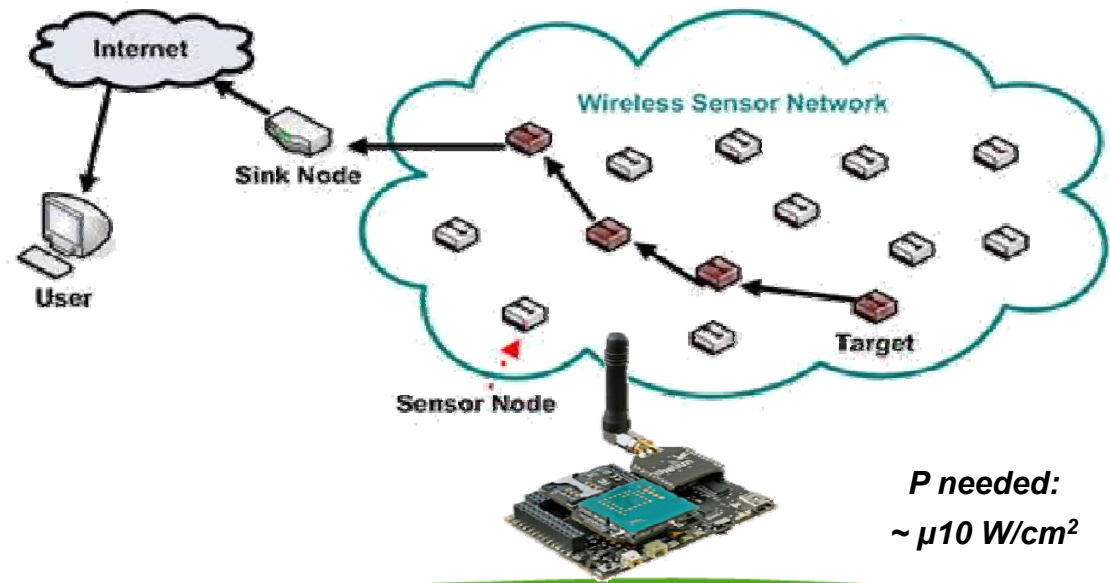
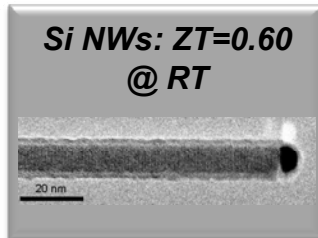
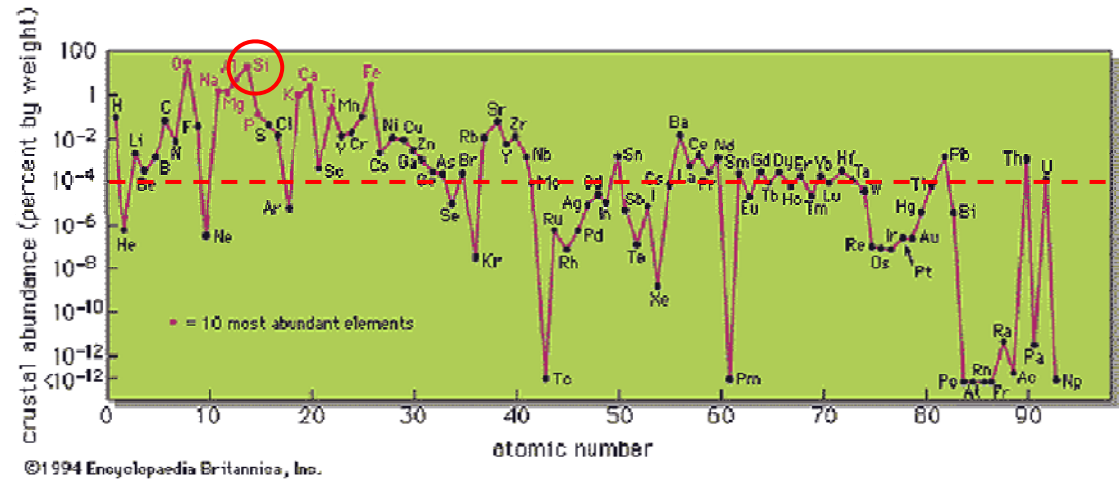
G. Gadea, A. Morata, J.D. Santos, I. Domnez, C. Calaza, M. Salleras,
D. Dávila, L. Fonseca, A. Tarancón

Lille, EMRS May 2016

Thermoelectric energy harvesting with silicon nanowires

Si NWs are promising materials TE energy harvesting because:

- Their high ZT with respect bulk
- The high availability of silicon
- The easy integrability in micro-technology (which is silicon-based!)



**P needed:
 $\sim \mu 10 \text{ W/cm}^2$**

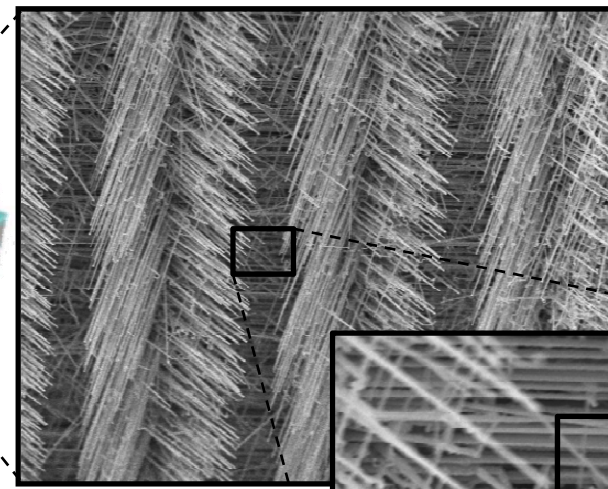
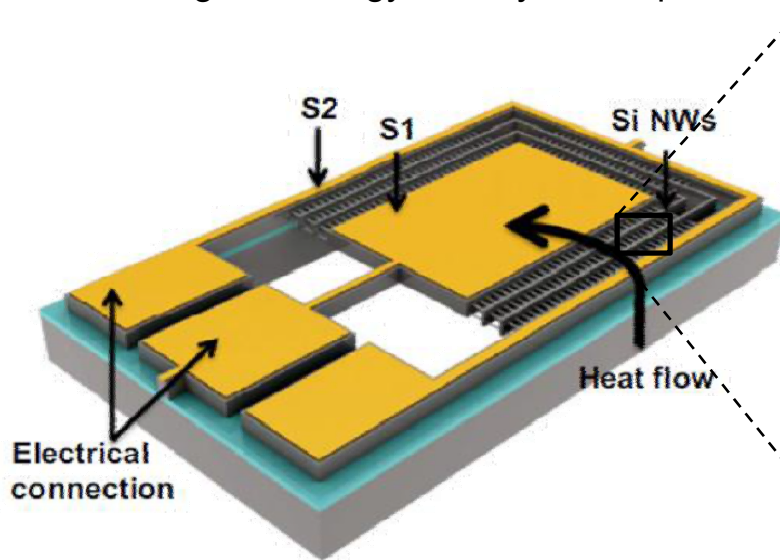
WSN node

Thermoelectric energy harvesting with silicon nanowires

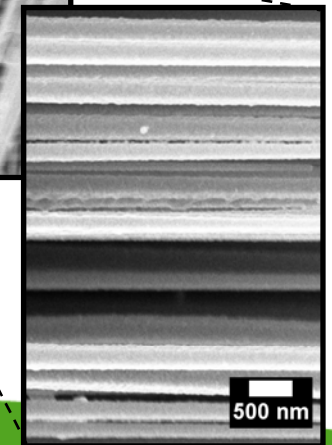
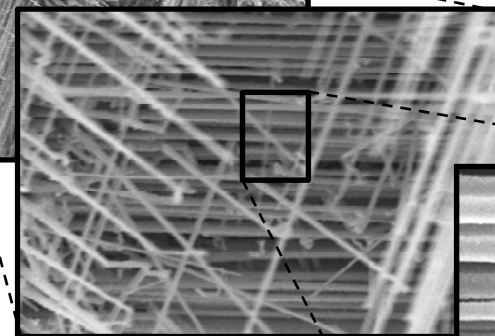
Integrating NWs in thermoelectric devices presents challenges:

- Contacting dense arrays of NWs / cm²
- NWs with low contact resistance
- Submitting NWs to large ΔT
- Using technology friendly techniques

For this we use a micro-machined **planar thermoelectric generator (μ TEG)**



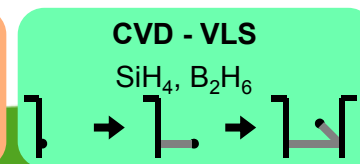
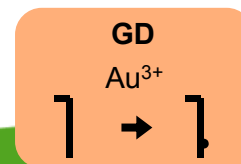
- **Length: 10 μ m**
- **Diameter: 100 nm**
- **Density: 1-5 NWs/ μ m²**
- **Epitaxial growth on Si**



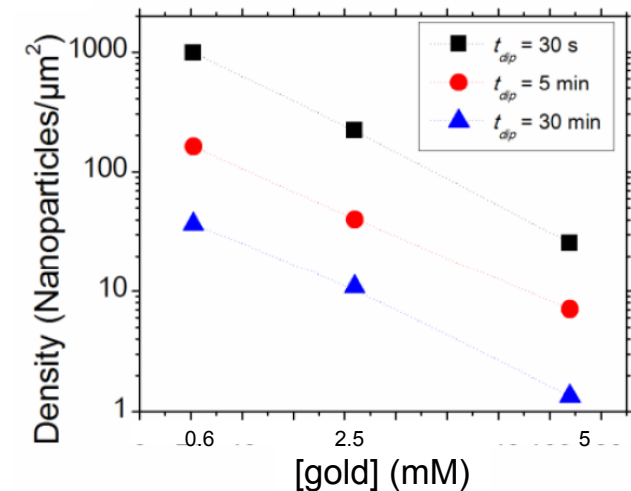
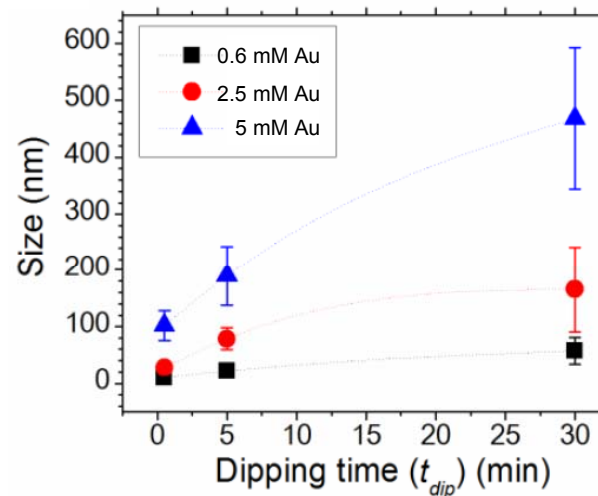
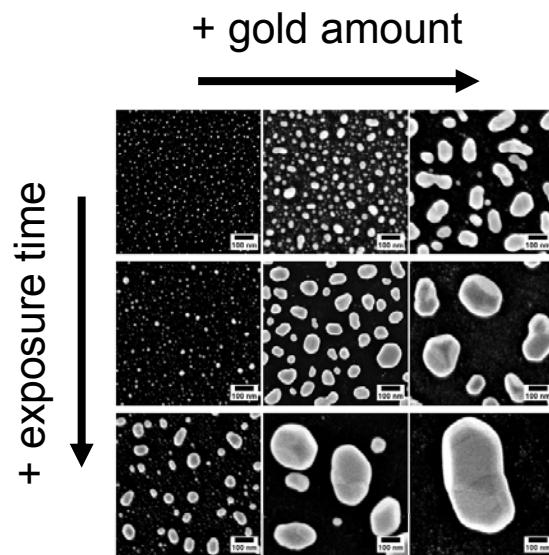
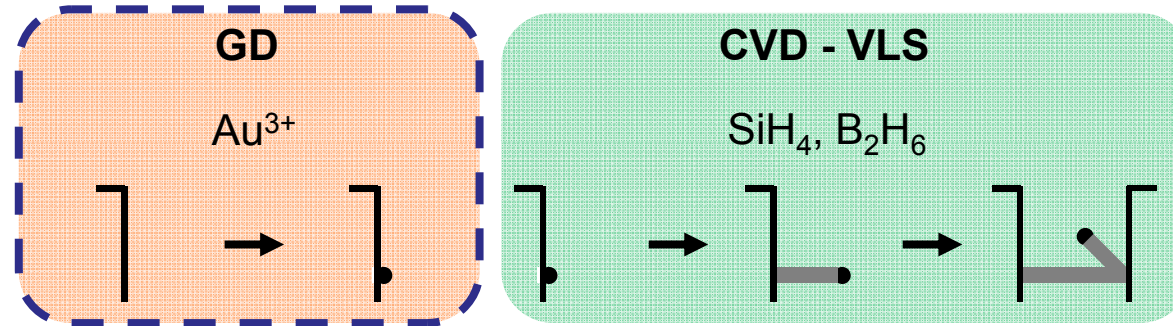
Silicon
 Silicon oxide
 Tungsten (contacts)

From D. Dávila et al. *Nano Energy*, 1(6), (2012) 812

Easy growth + integration

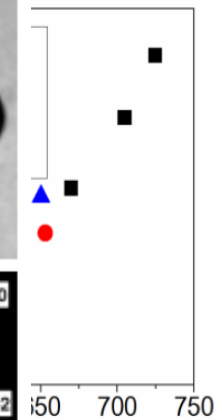
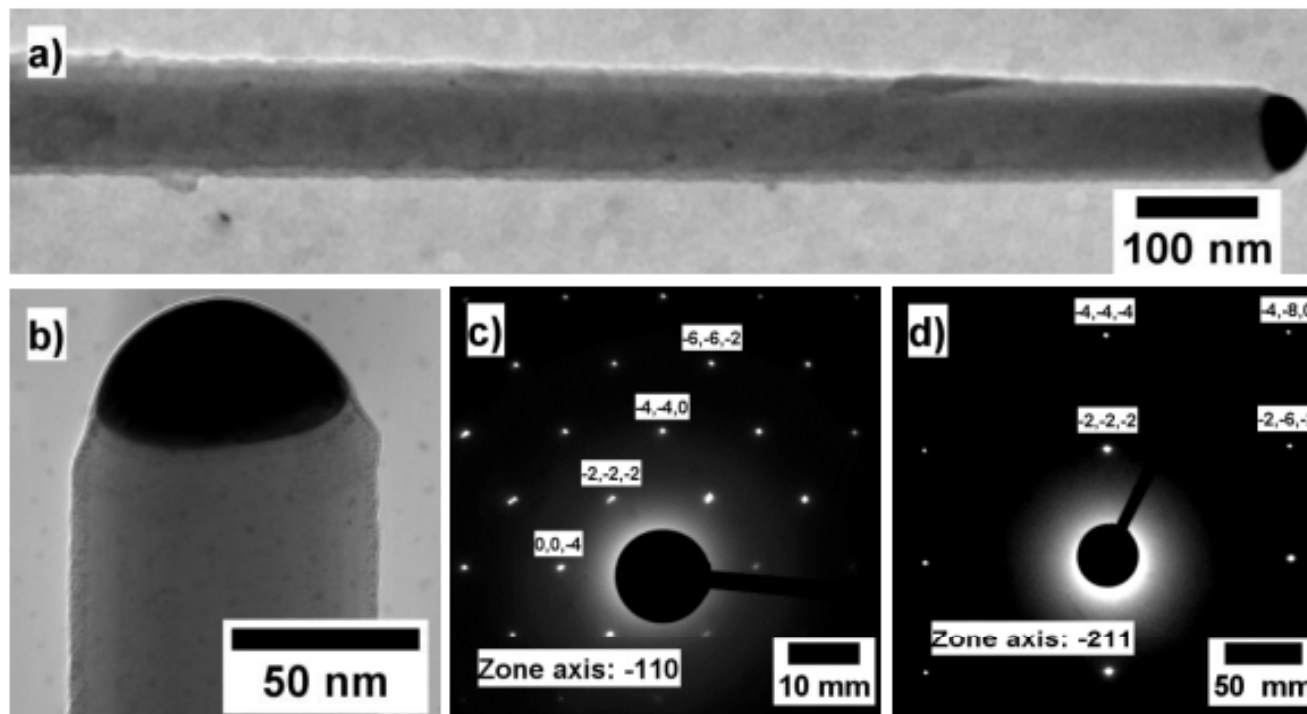
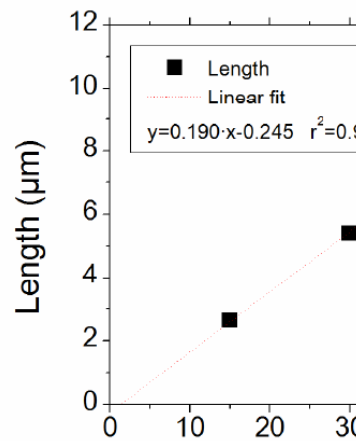
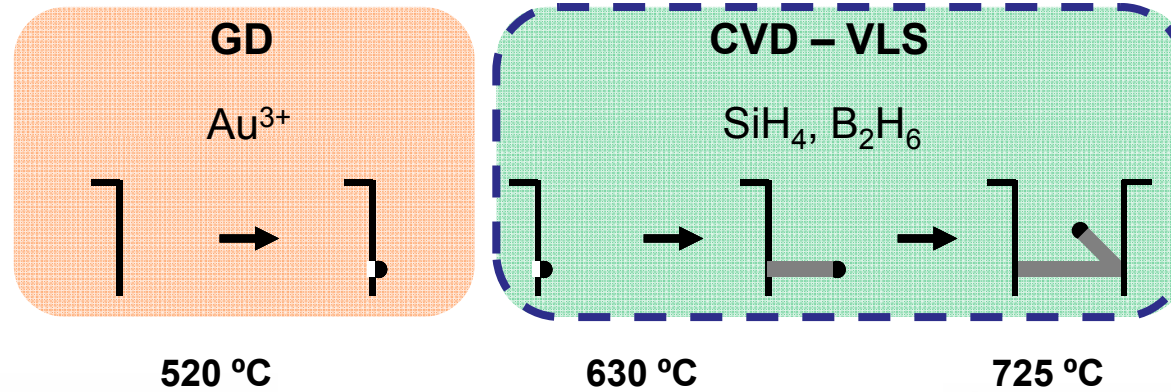


Silicon nanowire morphology control

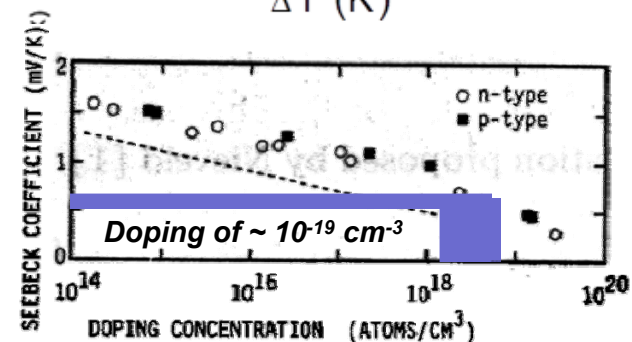
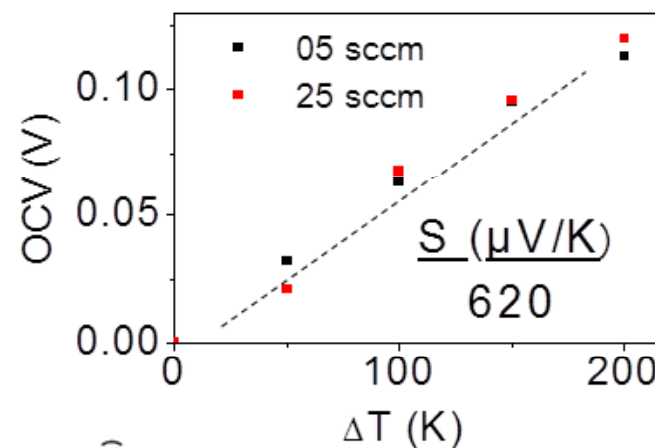
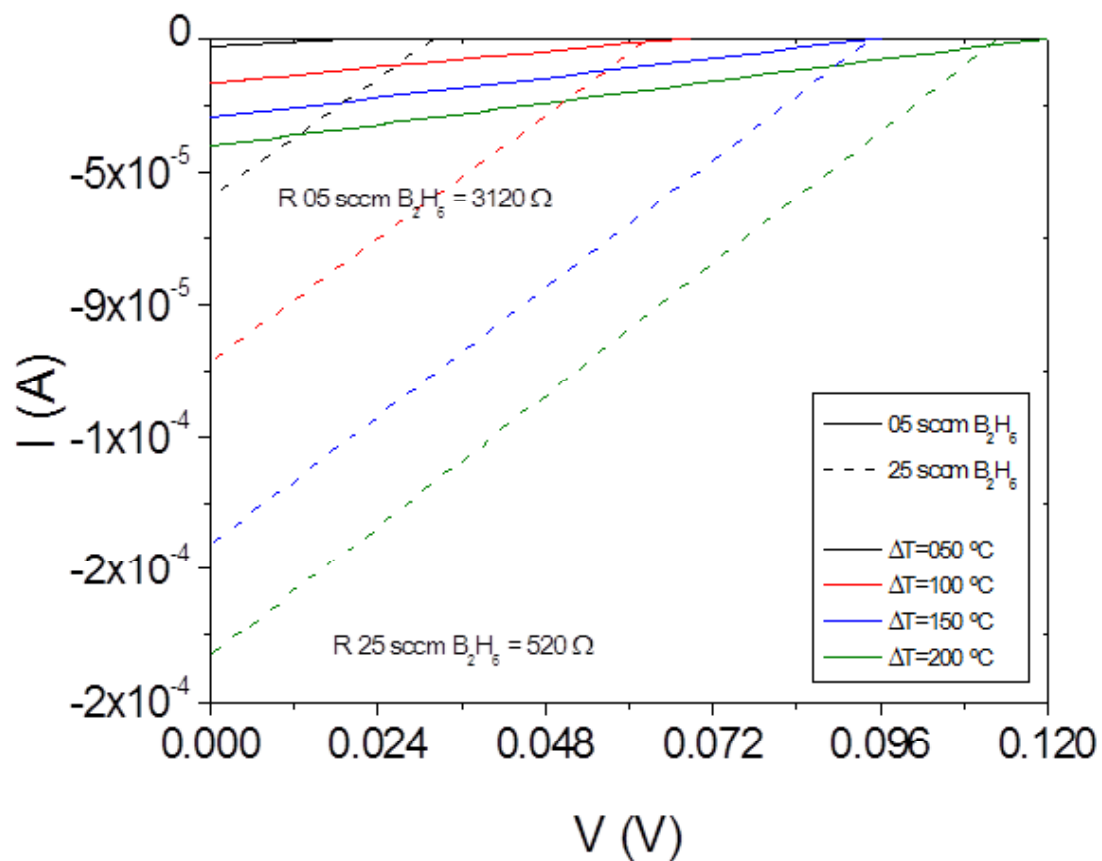


- Increasing the gold amount/exposure time, the nanoparticle size increases and while the density decreases

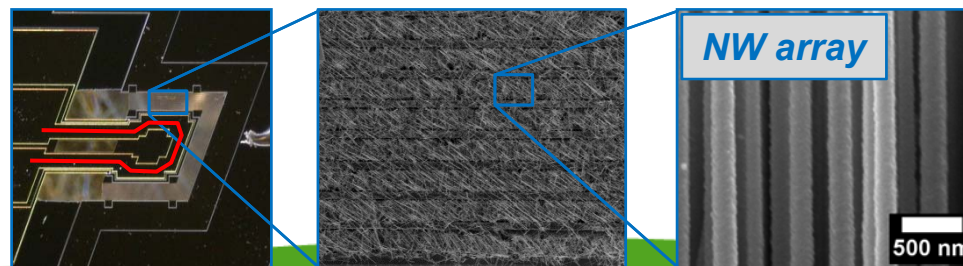
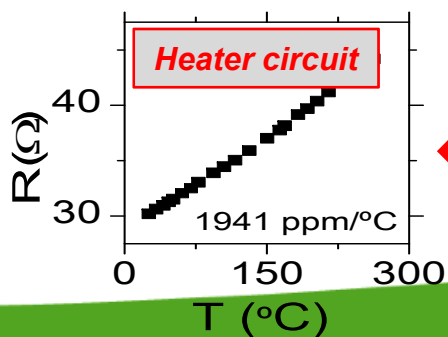
Silicon nanowire morphology control



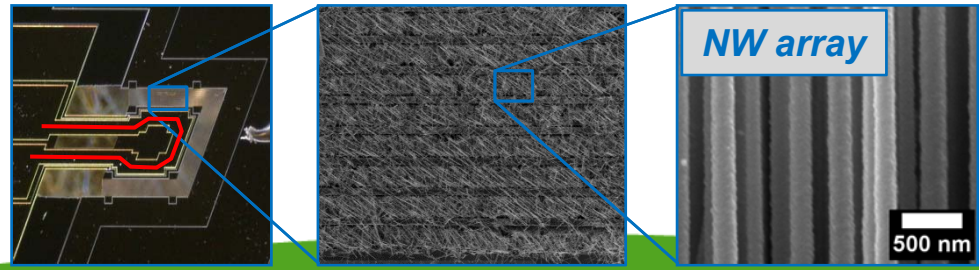
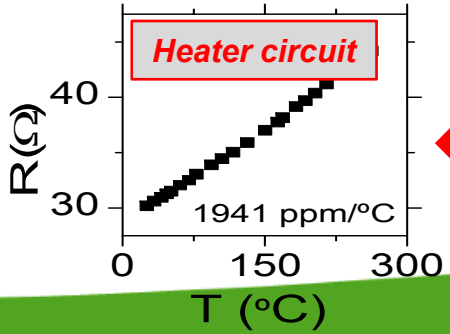
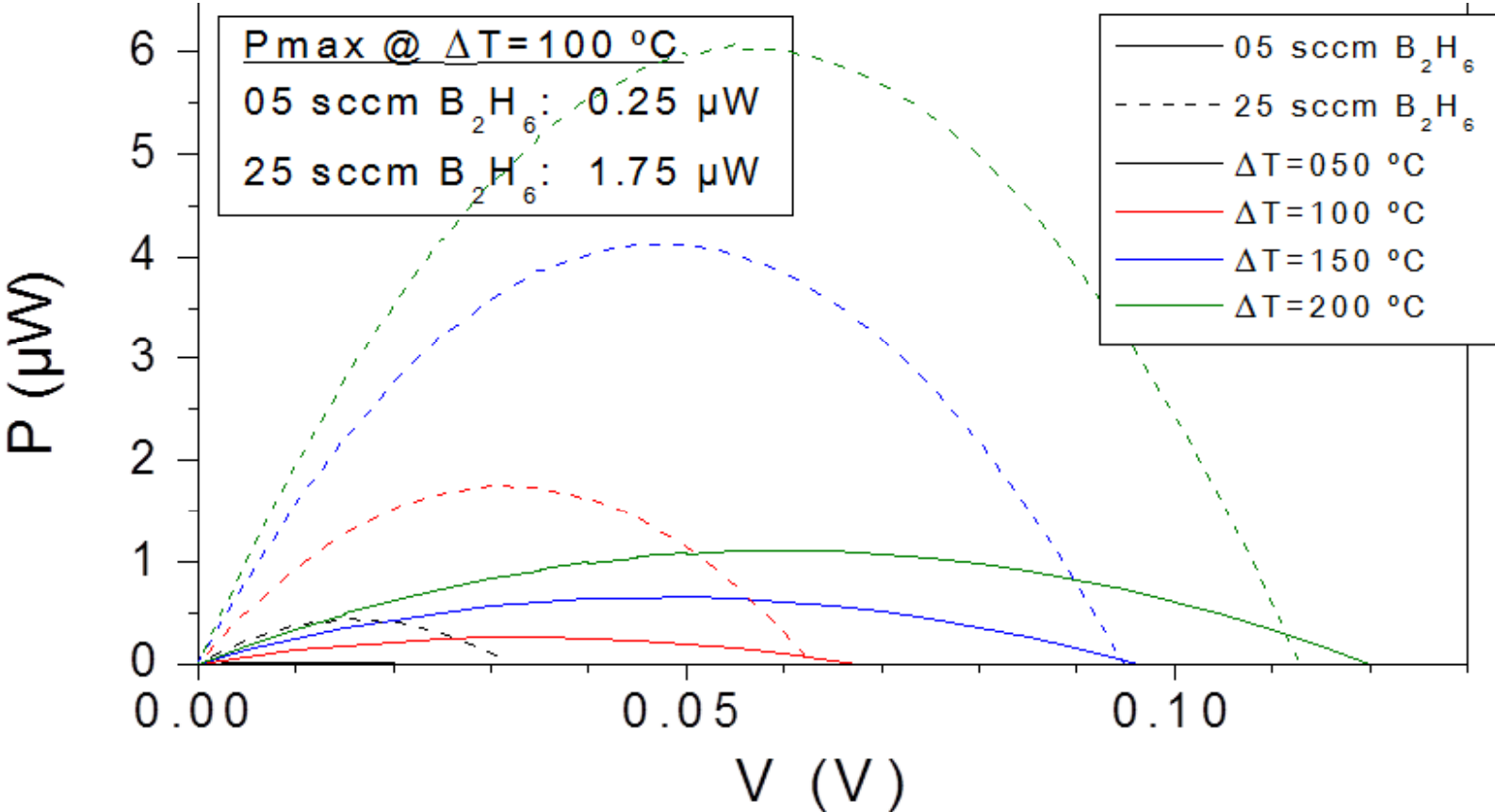
Integration in devices and effect of diborane flow



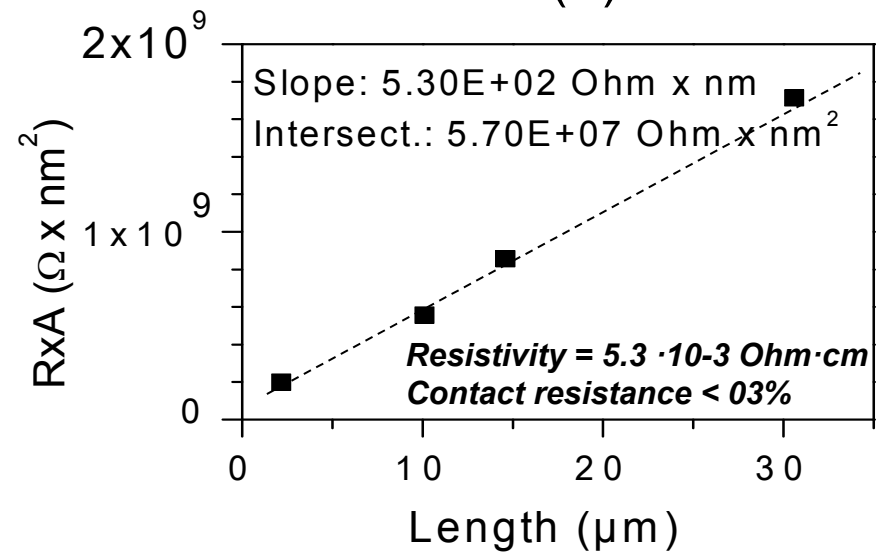
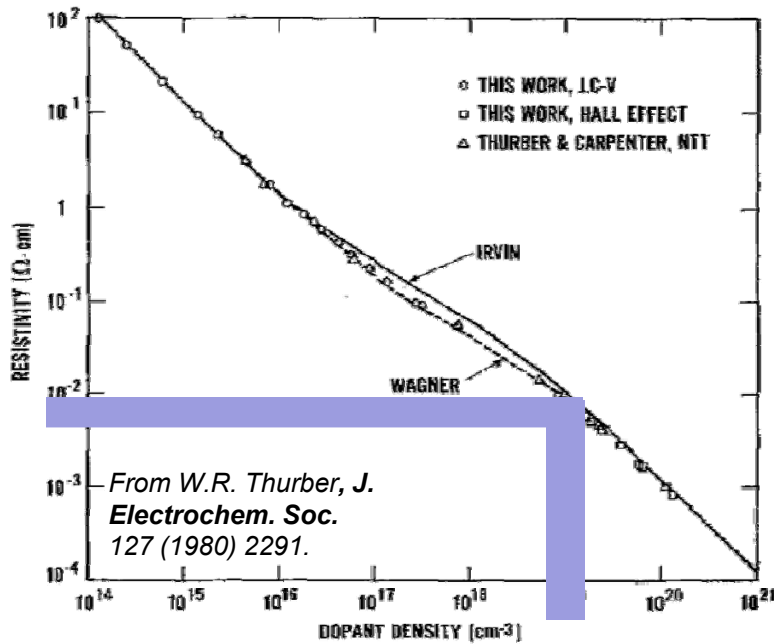
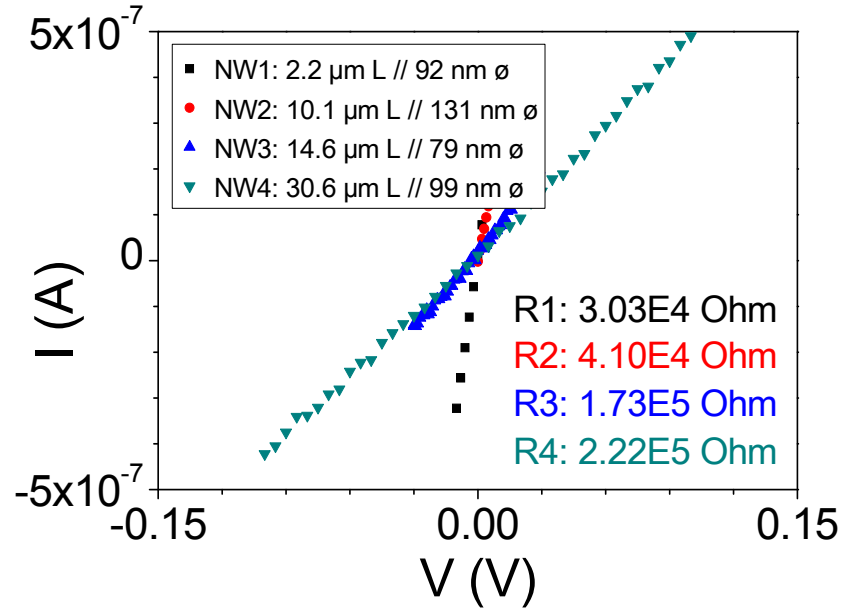
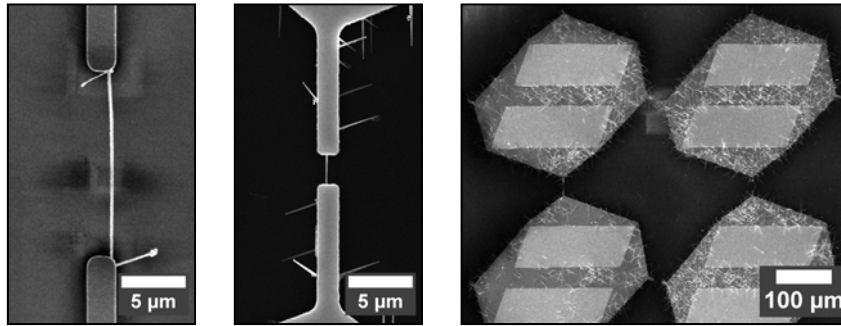
From A. Van Herwaarden, *Sensors and Actuators* 6 (1984) 245.



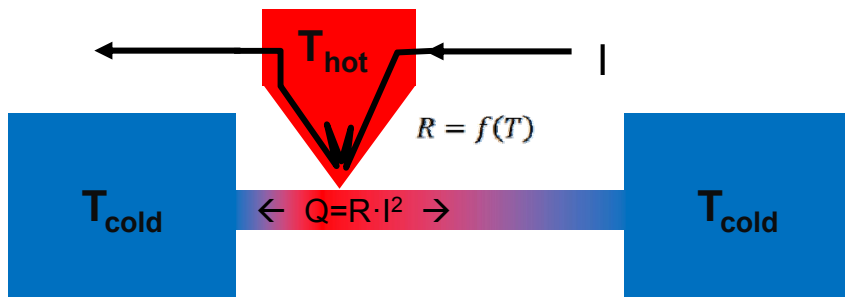
Integration in devices and effect of diborane flow



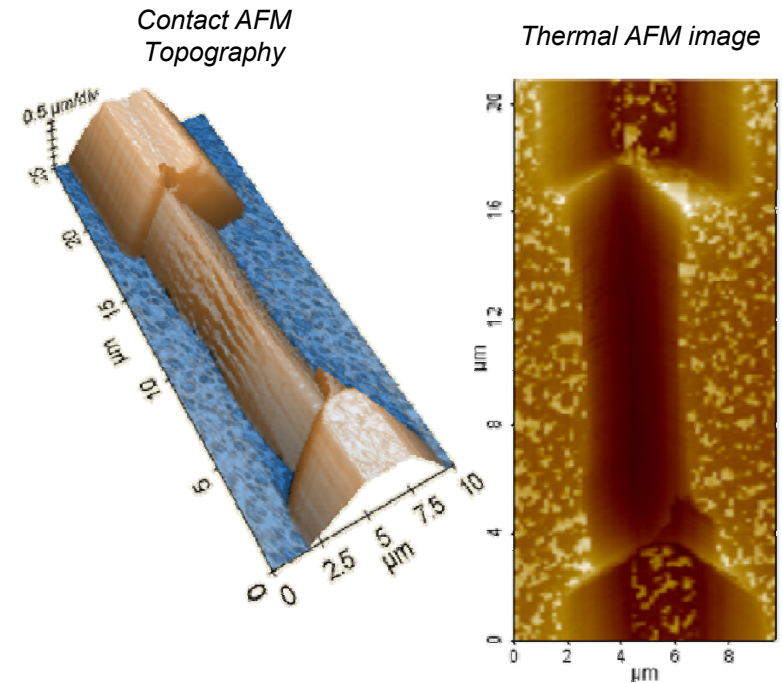
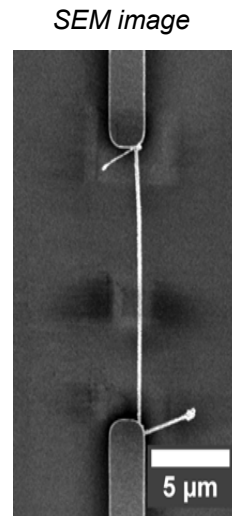
Single NW electrical measurements



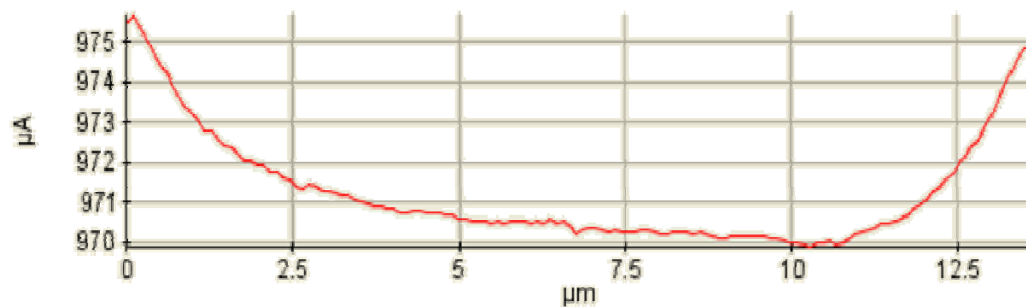
Single NW thermal AFM measurements



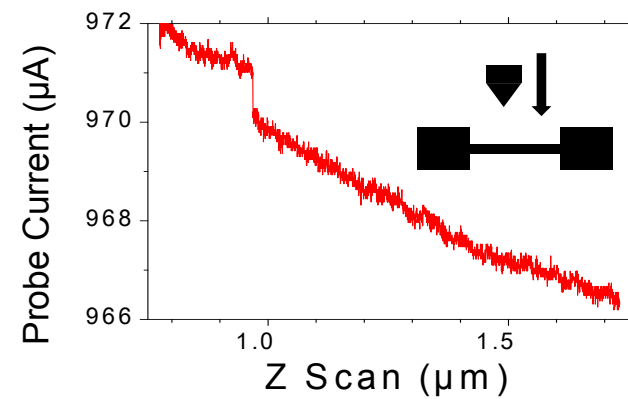
- The thermal afm tip can inject a known heat Q and measure T locally under the tip



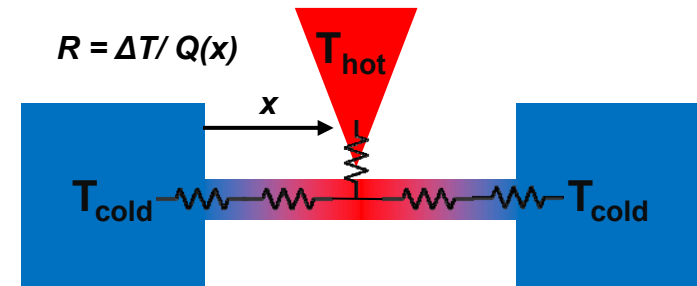
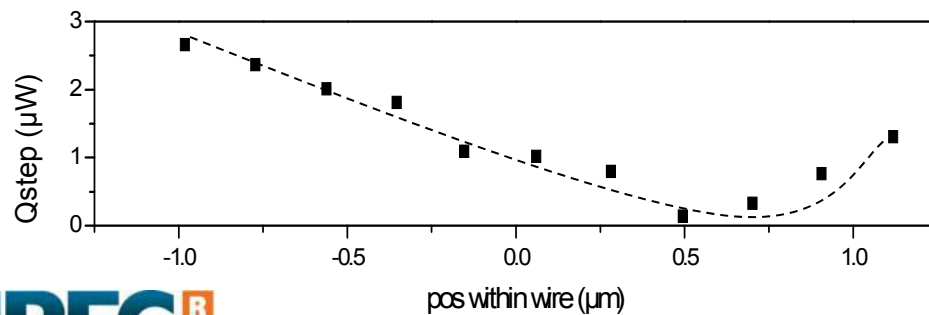
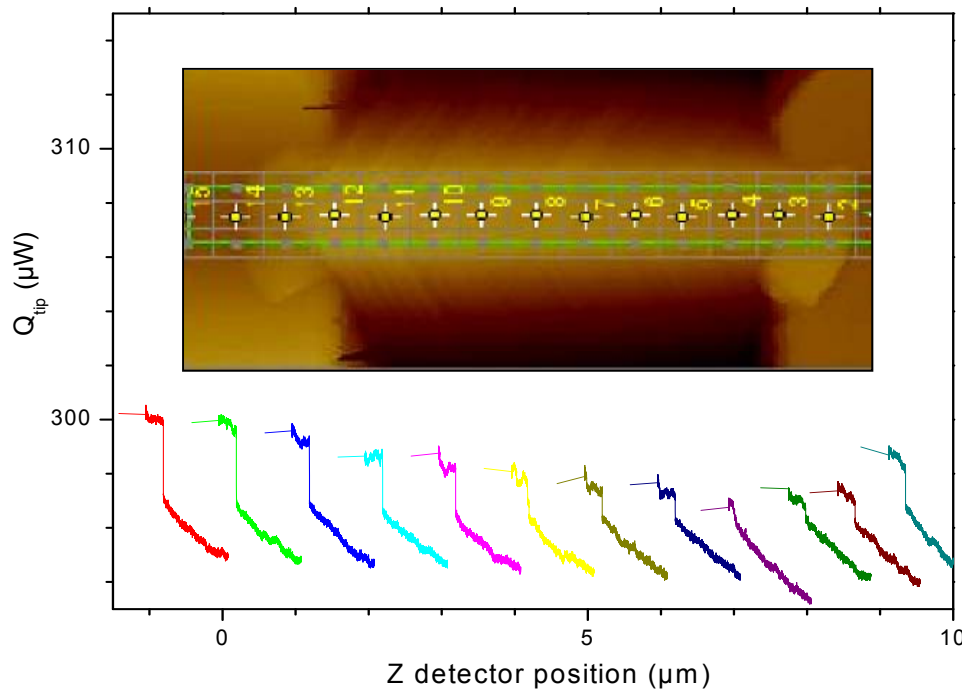
Line scan along the NW



Approach curve



Single NW thermal AFM measurements

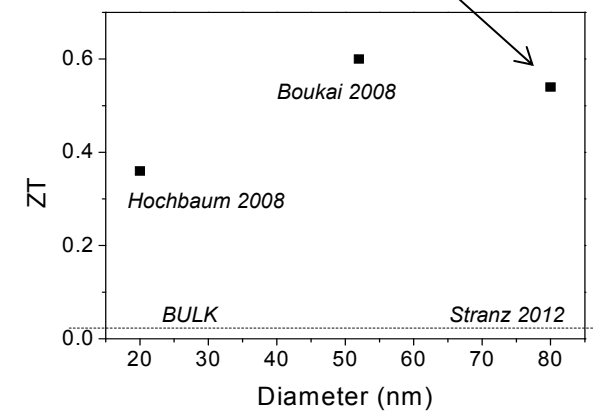


$$R = R_C + \frac{R_{NW}^2 \cdot f(x) + R_S \cdot R_{NW} + R_S^2}{R_{NW} + 2R_S}$$

$$R_{NW} = \frac{L}{A \cdot k_{NW}} \quad \longrightarrow \quad k_{NW} = 4 \text{ W/m}\cdot\text{K}$$

$$S = 620 \text{ } \mu\text{V/K} \quad \sigma = 190 \text{ } \Omega/\text{cm}$$

$$ZT @ RT = 0.54$$



Conclusions

- 111 Si NWs were grown. Their properties could be controlled through:
 - Au catalyst deposition (selective deposition, density and size)
 - CVD growth (length, doping)
- Si NWs arrays were integrated in thermoelectric microgenerators and characterized
 - Seebeck coefficient was 620 $\mu\text{V/K}$
 - Higher dopant flow led to higher power (25 $\mu\text{W/cm}^2$)
- Single Si NWs were integrated in thermoelectric characterization structures
 - Electrical resistivity was $5.3 \cdot 10^{-3} \Omega \cdot \text{cm}$ and negligible electrical contact resistance
 - Thermal conductivity was 4 $\text{W/m}\cdot\text{K}$ by, by means of **thermal AFM along a single wire**
- Combining the results a ZT of 0.54 at room temperature was obtained. ~ 25 times higher than bulk silicon value

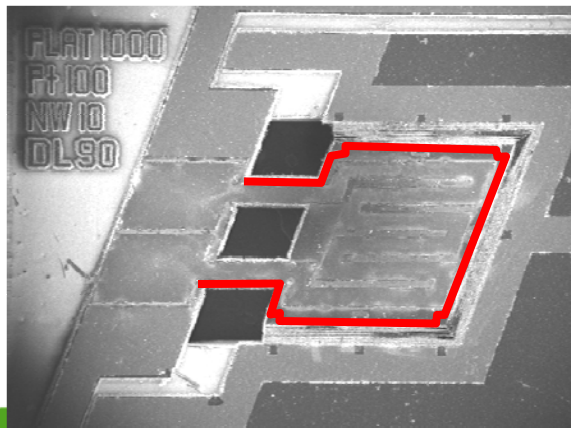
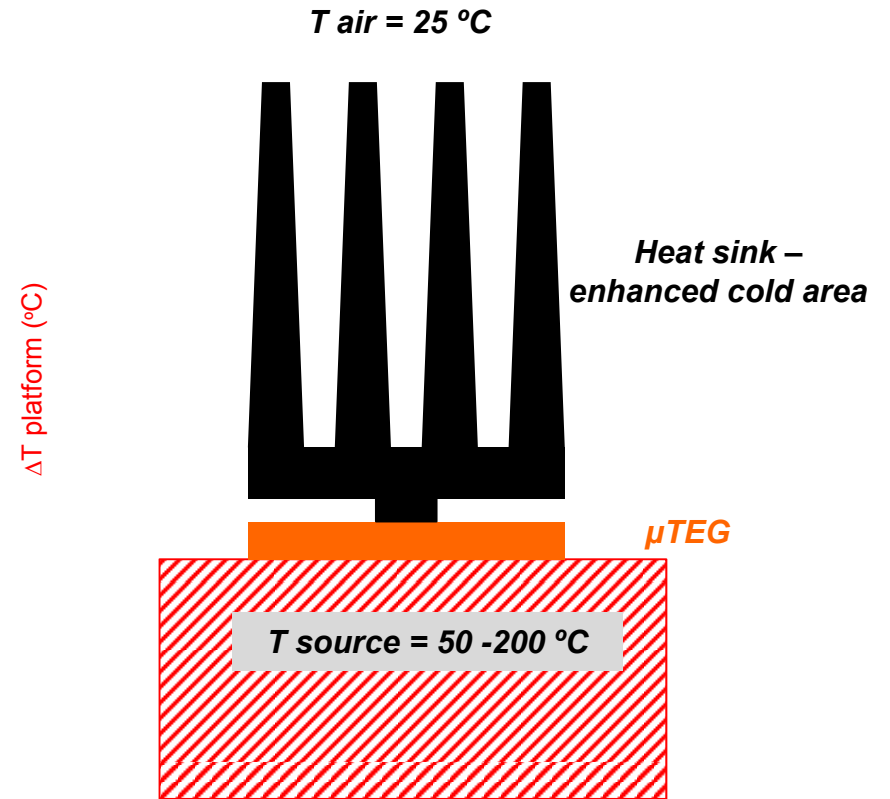
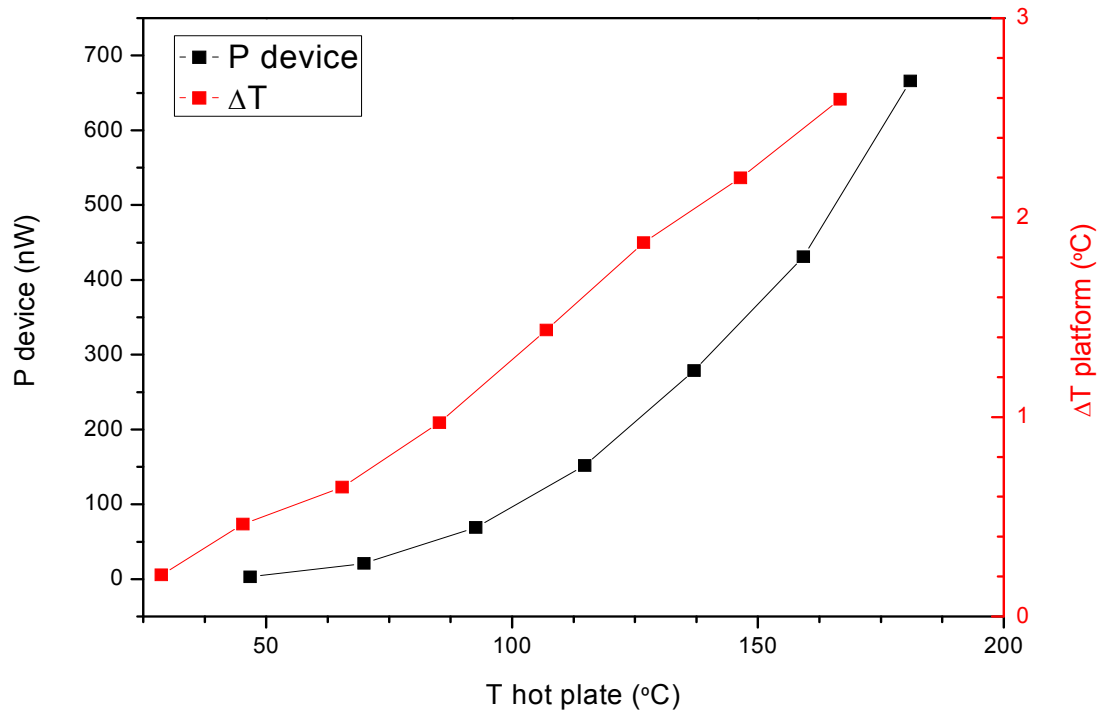
Acknowledgements

- **A. Morata**
- **J.D. Santos**
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- **C. Calaza**
- **M. Salleras**
- **D. Dávila**
- **L. Fonseca**
- **A. Tarancón**

And to IRECs NI-SOFC group



Device in harvesting mode



$1\text{ NW}/\mu\text{m}^2$

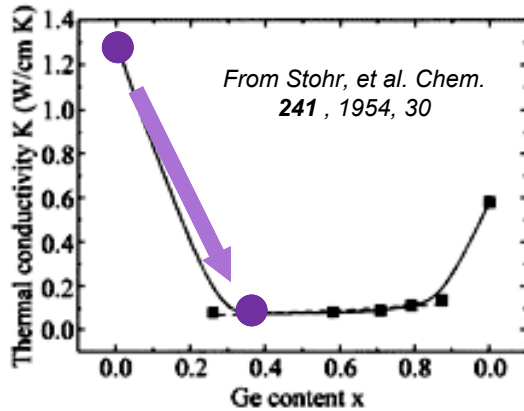
$5 \cdot 10^{-3}\text{ Ohm}\cdot\text{cm}$

$R_{\text{expected NW array}} = 1\ \Omega$

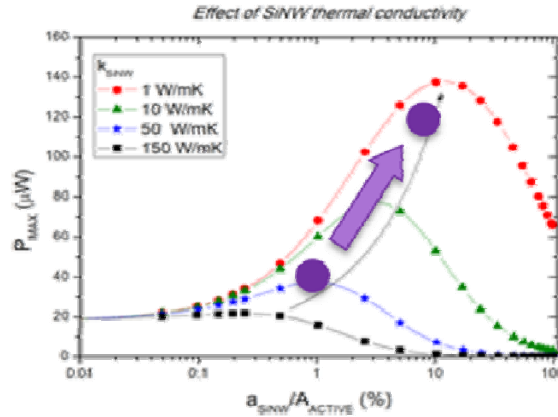
$R_{\text{measured NW array}} = 50\text{-}100\ \Omega$

$R_{\text{collector path}} = 200\ \Omega$

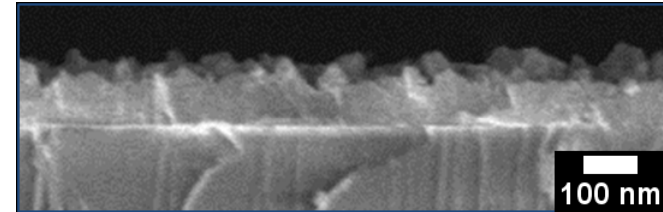
Growth of Si-Ge NWs for future integration in μ TEG



Si-Ge alloying should lead to a drastic reduction in NW thermal conductivity

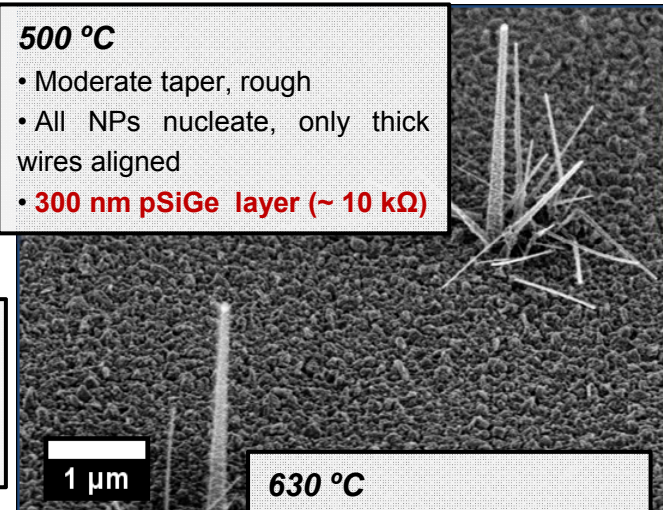


Implementation in devices is expected to increase the power by a factor of 5-10



500 °C

- Moderate taper, rough
- All NPs nucleate, only thick wires aligned
- **300 nm pSiGe layer (~ 10 k Ω)**

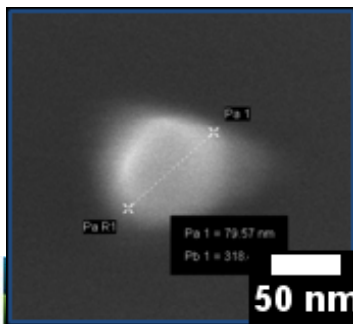


450 °C

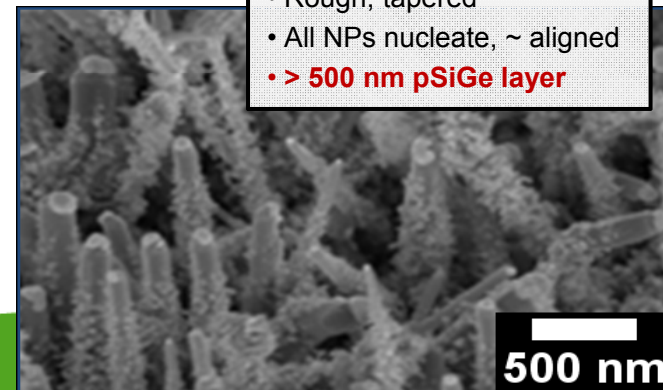
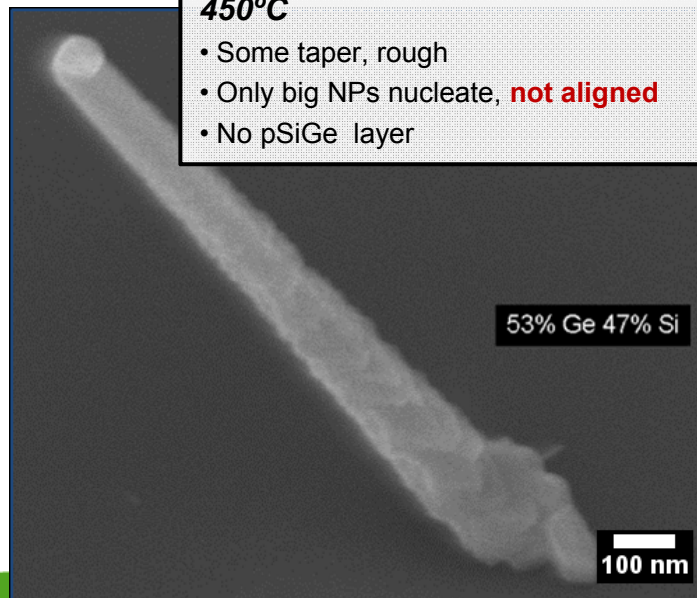
- Some taper, rough
- Only big NPs nucleate, **not aligned**
- No pSiGe layer

400 °C

- No nucleation at all
- No pSiGe layer



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630 °C

- Rough, tapered
- All NPs nucleate, ~ aligned
- **> 500 nm pSiGe layer**